EverTherm™

PRODUCT SELECTION GUIDE

CR Technology

Item	Grade Item	Thermal Conductivity	Hardness (shoreoo)
1	EVSF100	1.5w/mk	65
2	EVSF500	3.0w/mk	65
3	EVSF600	5.0w/mk	65
4	EVSF600G	6.0w/mk	65
5	EVSF800	8.0w/mk	65
6	EVSF1000	10.0w/mk	65
7	EVSF1200	12.0w/mk	65
8	EVAF800	8.0w/mk	65
9	EVAF100	1.0w/mk	75
10	EVAF500	3.0w/mk	75
11	EVAF600G	5.0w/mk	75
12	EVAF800	8.0w/mk	75
13	EVSA408FG	1.0w/mk	**
14	EVSC800FG	0.8w/mk	45
15	EVSC800-PI-2-K4	0.9w/mk	90
16	EVSC800-PI-2-K10	1.3w/mk	90
17	EVSC900FG	2.0w/mk	45
18	EVSC900FG-A1	2.0w/mk	45

Item	Grade Item	Thermal Conductivity	Hardness (shoreoo)
19	EVSC1000FG	3.5w/mk	90
20	EVSF100	1.5w/mk	25
21	EVSF100FG	1.5w/mk	70
22	EVSF100FG-A1	1.5w/mk	90
23	EVSF300	2.0w/mk	60
24	EVSF400	2.5w/mk	75
25	EVSF500	3.0w/mk	75
26	EVSF600	5.0w/mk	75
27	EVSF600G	6.0w/mk	80
28	EVSF800	8.0w/mk	80
29	EVSH600	<0.1w/mk	20
30	EVSP205A	3.0w/mk	**
31	EVSP350P	1.8w/mk	**
32	EVSR600-A-B	1500w/mk	**
33	EVSR600-A-P	1500w/mk	**
34	EVCSF25	25w/mk	**
35	EVSU010-1/2	400w/mk	**
36	EVSY300	0.018w/mk	**

EverTherm™

Technical Data Sheet

EVSF100

Product Description

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness options to easily solve any heat related issue. EVERTHERM pads are naturally tacky and can be cut to any size or shape for easy installation. EVERTHERM pads are designed and engineered to achieve the highest level of thermal management to protect today's most advanced electronics.

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Color	White	Visual
Thickness	0.15-15.0mm	ASTM D374
Specific Gravity	2.1g/cc	ASTM D792
Thermal Conductivity	1.5 W/m-K	ASTM D5470
Hardness (Shore OO)	15~90。	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	50psi	ASTM D412
Breakdown Voltage AC(KV)	＞2@0.5MM ＞4@0.75MM	ASTM D149
UL Flammability Rating	UL94 V-0	E355606
Volume Resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200℃	——
Thermal Resistance(1mm,@40psi)	0.9℃*in2/W	ASTM D5470
Compression Ratio(1mm,@40psi)	50%	——
Dielectric Constant MHz	5.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

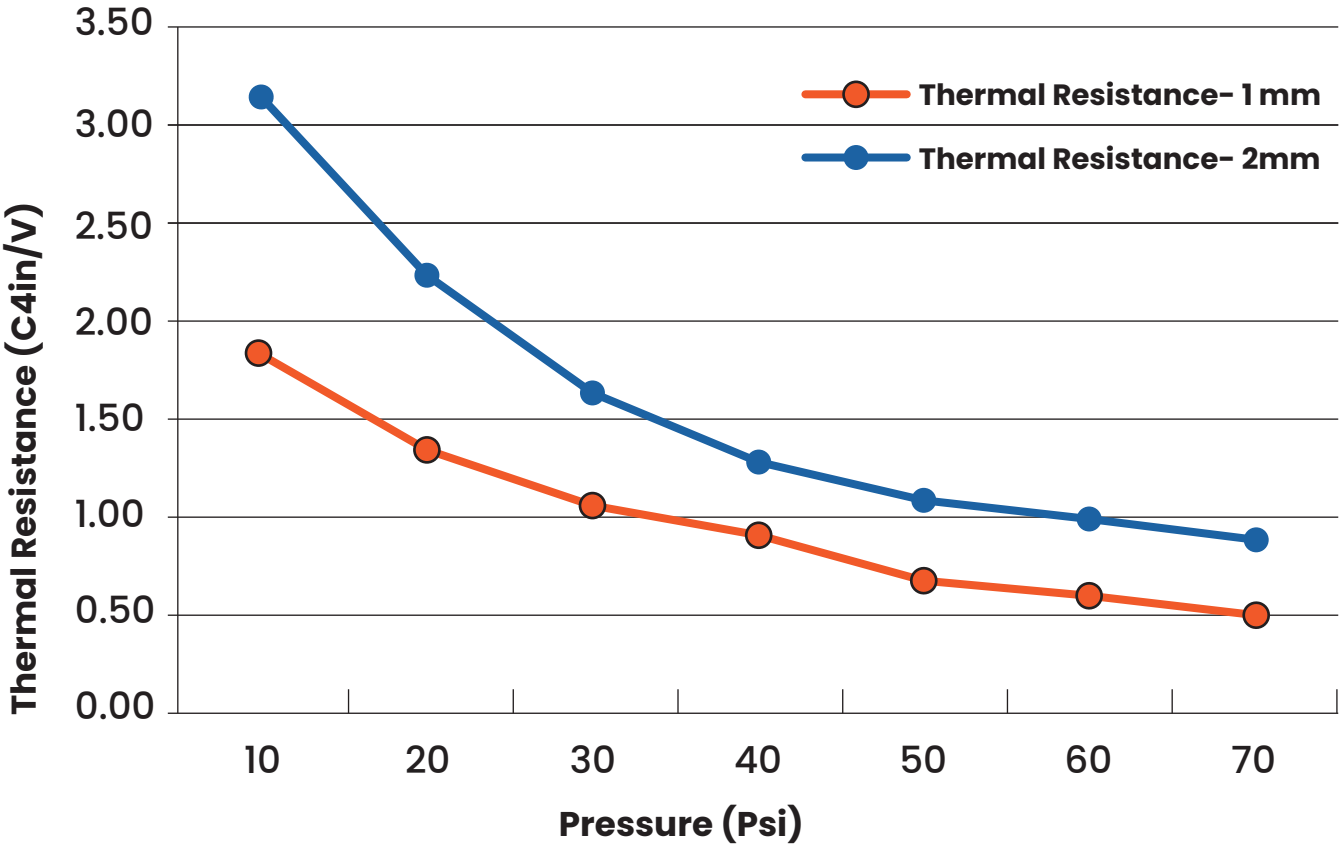
EverTherm™

EVSF100

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like:
  LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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EverTherm™

Technical Data Sheet

EVSF 500

Product Description

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Color	Blue	visual
Thickness	0.15 ~ 10.0mm	ASTM D374
Specific Gravity	2.9g/cc	ASTM D792
Thermal Conductivity	3.0 W/m-K	ASTM D5470
Hardness (Shore OO)	30	ASTM D2240
Elongation	60%	ASTM D412
Tensile Strength	45psi	ASTM D412
Breakdown Voltage AC(KV)	＞2@0.5MM ＞4@0.75MM	ASTM D149
UL Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200℃	——
Thermal Resistance(1mm,@40psi)	0.45℃*in2/W	ASTM D5470
Compression Ratio(1mm,@40psi)	35%	——
Dielectric Constant 1MHz	5.6	ASTM D150
RoHS (10)	PASS	IEC 62321
Halogen (4)	PASS	EN14582
REACH (191)	PASS	EN14372

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

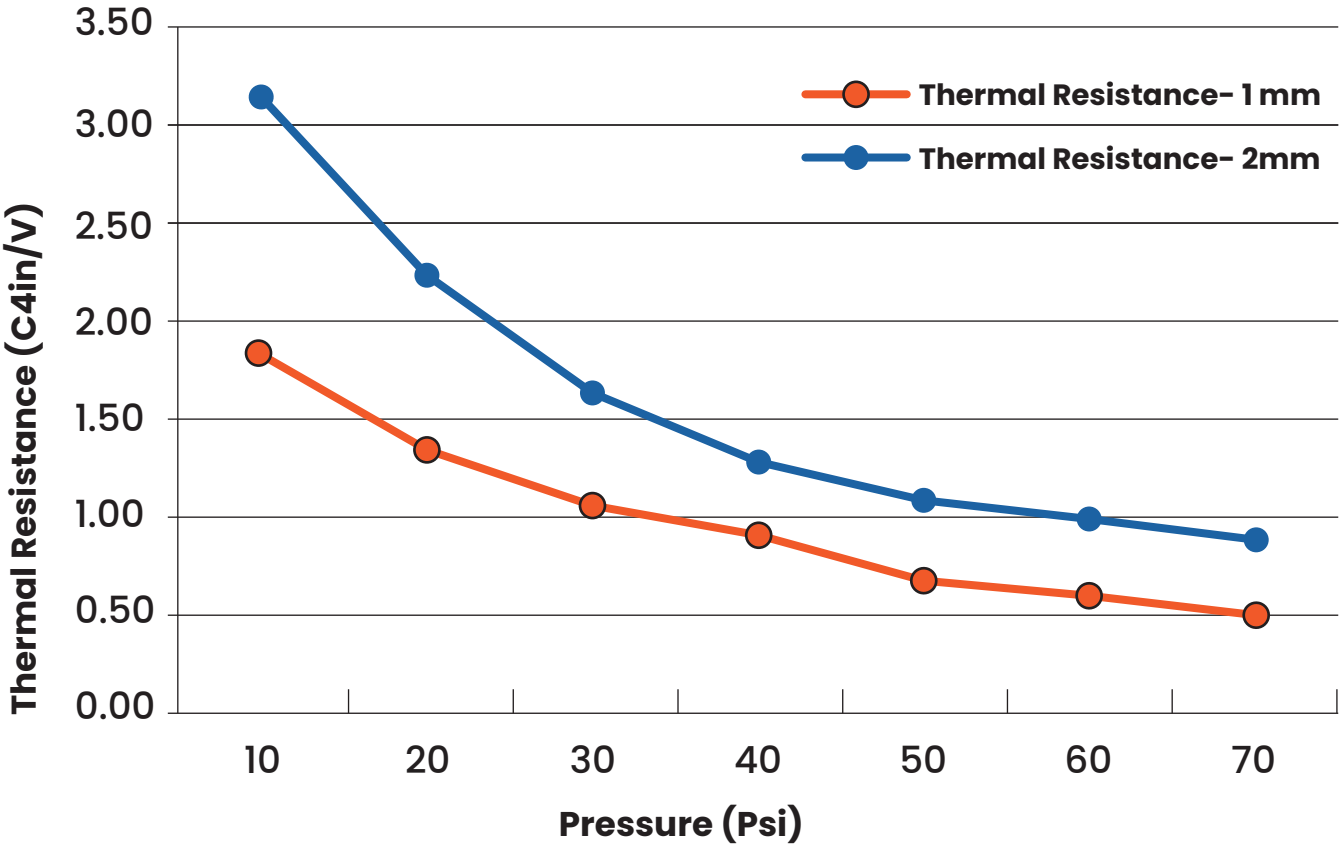
EverTherm™

EVSF 500

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like:
  LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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EverTherm™

Technical Data Sheet

EVSF 600G

Product Description

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Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Color	Gray	Visual
Thickness	0.5 ~ 5.0mm	ASTM D374
Specific Gravity	3.30g/cc	ASTM D792
Thermal Conductivity	6.0 W/m-K	ASTM D5470
Hardness (Shore OO)	60	ASTM D2240
Elongation	20%	ASTM D412
Tensile Strength	30psi	ASTM D412
Breakdown Voltage AC(KV)	＞2@0.5MM ＞4@0.75MM	ASTM D149
UL Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200℃	——
Thermal Resistance(1mm,@40psi)	0.29℃*in2/W	ASTM D5470
Compression Ratio(1mm,@40psi)	35%	——
Dielectric Constant 1MHz	5.8	ASTM D150
RoHS (10)	PASS	IEC 62321
Halogen (4)	PASS	EN14582
REACH (191)	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

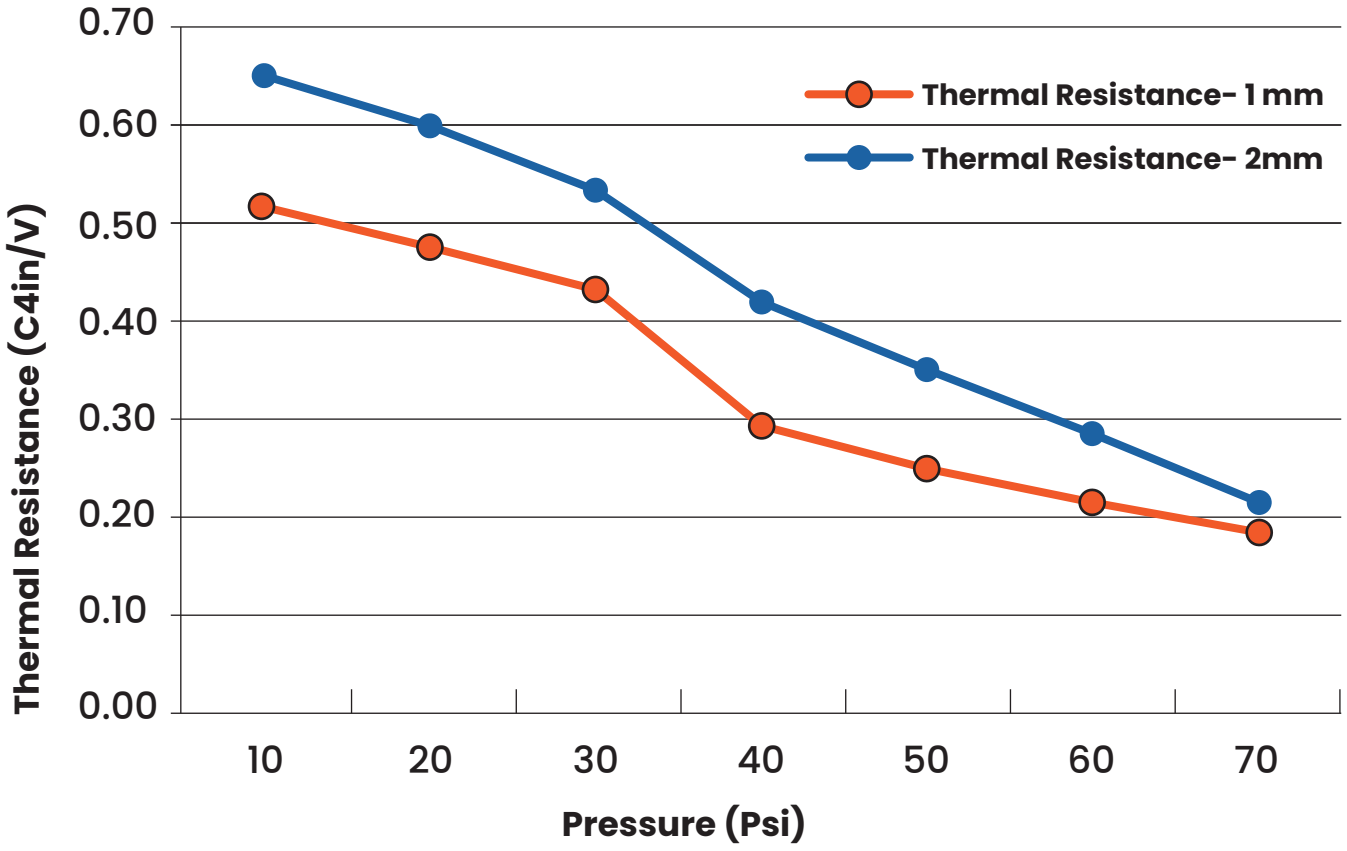
EverTherm™

EVSF 600G

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like:
  LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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EverTherm™

Technical Data Sheet

EVSF800

Product Description

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Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Color	Gray	visual
Thickness	0.5 ~ 5.0mm	ASTM D374
Specific Gravity	3.40g/cc	ASTM D792
Thermal Conductivity	8.0 W/m-K	ASTM D5470
Hardness (Shore OO)	50	ASTM D2240
Elongation	15%	ASTM D412
Tensile Strength	10psi	ASTM D412
Breakdown Voltage AC(KV)	>2@0.5MM >4@0.75MM	ASTM D149
UL Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50~ 200℃	——
Thermal Resistance(1mm,@40psi)	0.29℃*in2/W	ASTM D5470
Compression Ratio(1mm,@40psi)	15%	——
Dielectric Constant 1MHz	5.5	ASTM D150
RoHS (10)	PASS	IEC 62321
Halogen (4)	PASS	EN14582
REACH (191)	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

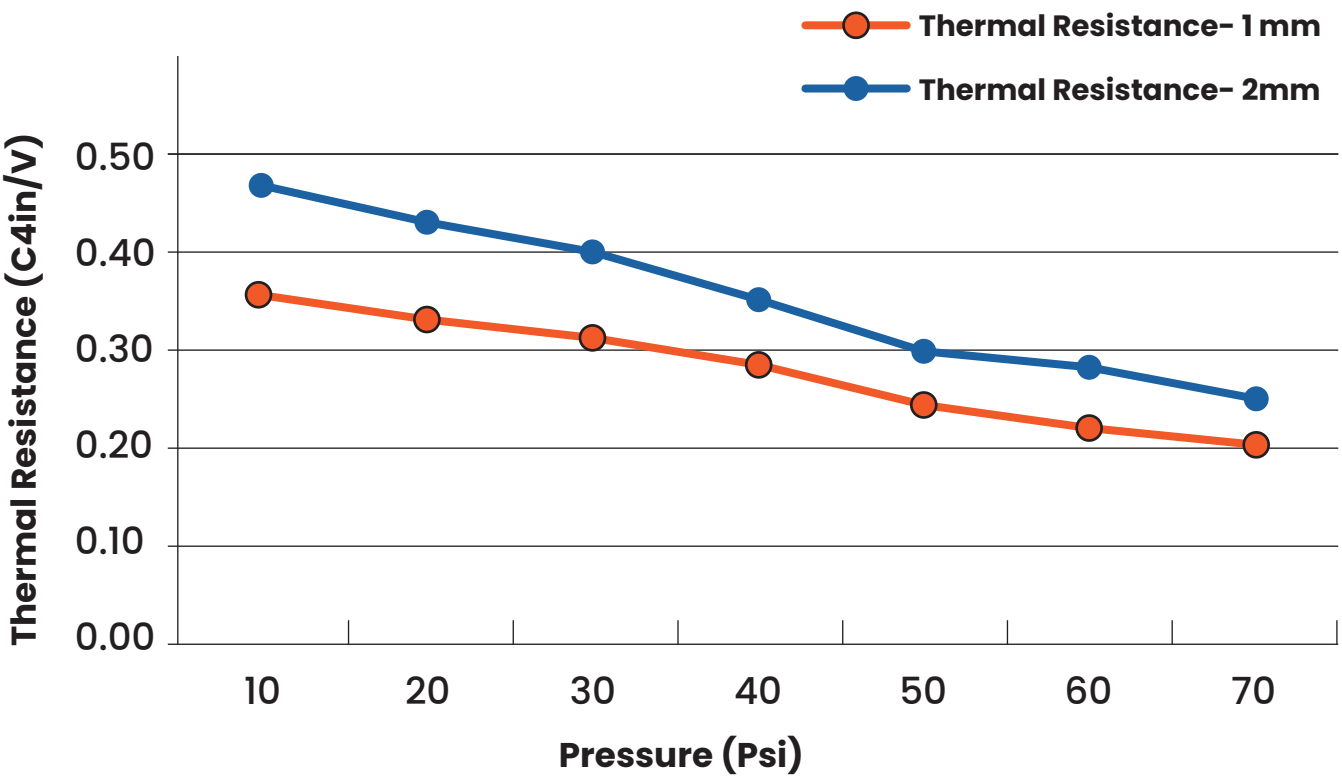
EverTherm™

EVSF800

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like:
  LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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EverTherm™

Technical Data Sheet

EVSF1000

Product Description

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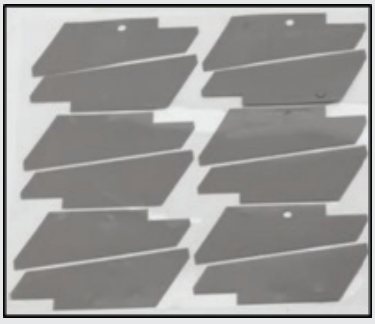


Color	Gray	visual
Thickness	0.5-5.0mm	ASTM D374
Specific Gravity	3.40g/cc	ASTM D792
Thermal Conductivity	10.0 W/m.K	ASTM D5470
Hardness (Shore OO)	55~75°	ASTM D2240
Elongation	15%	ASTM D412
Breakdown Voltage AC(KV)	＞2@0.5MM ＞4@0.75MM	ASTM D149
Oil yield	< 2%	***
UL Flammability Rating	V-0	UL 94
Volume Resistivity	1*1012Ω.cm	ASTM D257
Operating Temperature	-50~ 150℃	***
Thermal Resistance(1mm,@30psi)	0.12℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	≥15%	***
Dielectric Constant MHz	5.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

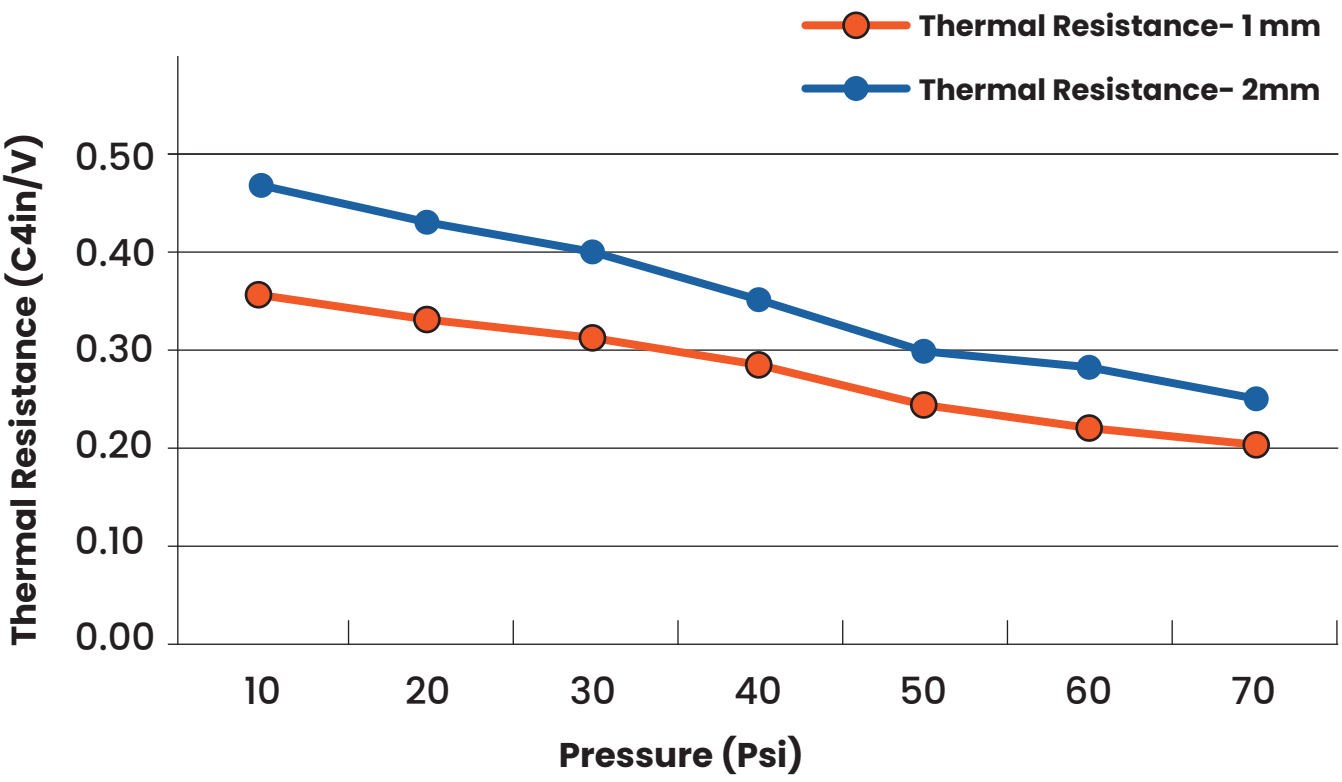
EverTherm™

EVSF1000

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like:
  LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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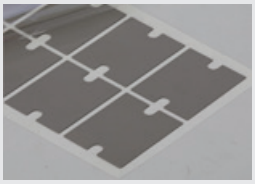
EverTherm™

Technical Data Sheet

EverTherm non-silicone thermal pads are manufactured from an advanced resin. They will not damage or promote circuit failure and have no siloxane volatilization resulting in no silicone oil seeping. EverTherm Non Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



EVAF800 NON-SILICONE

Color	Light Gray	Visual
Thickness	0.5 ~ 5.0mm	ASTM D374
Specific Gravity	3.4g/cm3	ASTM D792
Thermal Conductivity	8.0 W/m.k	ASTM D5470
Hardness(shore 00)	40-80	ASTM D2240
Normal Hardness(shore00)	50、70±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	UL
Volume Resistivity	1*1011Ω.cm	ASTM D257
Operating Temperature	-40~ 120℃	***
Thermal Resistance(1mm,@30psi)	0.20℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	20%	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

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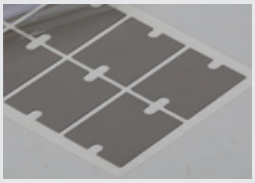

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVAF500 NON-SILICONE

Color	White	Visual
Thickness	0.25 ~ 5.0mm	ASTM D374
Specific Gravity	2.9g/cm3	ASTM D792
Thermal Conductivity	3.0 W/m.k	ASTM D5470
Hardness(shore 00)	40-80	ASTM D2240
Normal Hardness(shore00)	50/70±5	ASTM D2240
Elongation	70%	ASTM D412
Tensile Strength	55psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000v/mm	ASTM D149
Flammability Rating	UL94 V-0	UL
Volume Resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-40~ 130 °	***
Thermal Resistance(1mm,@30psi)	0.6℃ *in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	30%	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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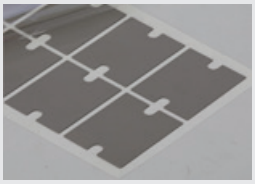
EverTherm™

Technical Data Sheet

EverTherm non-silicone thermal pads are manufactured from an advanced resin. They will not damage or promote circuit failure and have no siloxane volatilization resulting in no silicone oil seeping. EverTherm Non Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVAF600G NON-SILICONE

Color	Pink	Visual
Thickness	0.5-5.0mm	ASTM D374
Specific Gravity	3.1g/cm3	ASTM D792
Thermal Conductivity	6.0 W/m.k	ASTM D5470
Hardness(shore 00)	40-80	ASTM D2240
Normal Hardness(shore00)	50、70±5	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	30Psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	UL
Volume Resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-40 ~ 120℃	***
Thermal Resistance(1mm,@30psi)	0.25℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	20%	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

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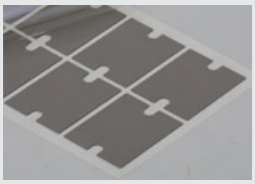

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVAF800 NON-SILICONE

Color	Light Gray	Visual
Thickness	0.5 ~ 5.0mm	ASTM D374
Specific Gravity	3.4g/cm3	ASTM D792
Thermal Conductivity	8.0 W/m.k	ASTM D5470
Hardness(shore 00)	40-80	ASTM D2240
Normal Hardness(shore00)	50、70±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	UL
Volume Resistivity	1*1011Ω.cm	ASTM D257
Operating Temperature	-40~ 120℃	***
Thermal Resistance(1mm,@30psi)	0.20℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	20%	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

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EverTherm™

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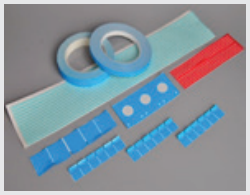
EverTherm thermal tape is widely used in bonding heat sinks to microprocessors and power consuming semiconductors. It features a high adhesive strength and low thermal impedance, which can effectively replace silicone grease and mechanical fixation.



Material Properties

- High-strength viscosity suitable for various surfaces
- Double-sided pressure-sensitive adhesive tape
- High thermal conductive acrylic adhesive
- Can withstand long-term high temperature working environment

Applications

- LED lighting products
- Chassis, frame or other cooling components
- Large capacity drive
- Heat pipe assembly
- RDRAM memory
- High frequency micro processing chip
- Notebook and desktop computers

EVSA408FG

Color	White	Visual
Substrate	Acrylic resin (Acrylic)	***
Substrate reinforcement	Fiberglass	***
Thickness(mm)	0.20±0.01	ASTM D374
Dielectric Breakdown Voltageh@AC	>4000V	ASTM D149
Release force	1.8kg/25mm	PSTC-3
Shear strength1.0 kg loading on 25 mm x 25 mm	> 48 hrs	PSTC-7
Heat resistance0.5kg loading on25mm x 25mm at 80	> 24 hrs	***
Thermal conductivity (W/m.k)	1.0	ASTM D5470
Operating temperature( )	-30 ~ 130	***
RoHS	PASS	IEC 62321
Halogen	PASS °	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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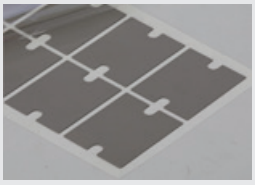

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

CR Technology

EVSF1200

Color	Gray	Visual
Thickness	0.8 ~ 5.0mm	ASTM D374
Specific Gravity	3.40g/cm3	ASTM D792
Thermal Conductivity	12.0 W/m.k	ASTM D5470
Hardness(Shore oo)	40-80	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	15%	ASTM D412
Dielectric Breakdown Voltageh@AC	>5000V/mm	ASTM D149
Flammability Rating	UL94 V0	UL
Oil Yield	< 2%	***
Volume Resistivity	1*1012Ω.cm	ASTM D257
Operating Temperature	-50~ 125℃	***
Thermal Resistance(1mm,@30psi)	0.10℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	≥15%	***
Dielectric Constant @1MHz	12.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

CR Technology, Inc

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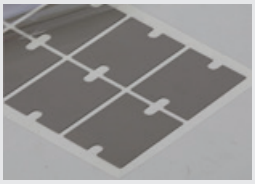
EverTherm™

Technical Data Sheet

EverTherm non-silicone thermal pads are manufactured from an advanced resin. They will not damage or promote circuit failure and have no siloxane volatilization resulting in no silicone oil seeping. EverTherm Non Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVAF100 NON-SILICONE

Color	White	Visual
Thickness	0.25 ~ 5.0mm	ASTM D374
Specific Gravity	1.9g/cm3	ASTM D792
Thermal Conductivity	1.0 W/m.k	ASTM D5470
Hardness(shore 00)	40-80	ASTM D2240
Normal Hardness(shore00)	50/70±5	ASTM D2240
Elongation	100%	ASTM D412
Tensile Strength	75psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	UL
Volume Resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-40 ~ 130℃	***
Thermal Resistance(1mm,@30psi)	1.10℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	30%	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

Technical Data Sheet

EverTherm SC Series is a thermally conductive silicone tape offering high temperature capability and conformability. Fiberglass fabric supports the thermally conductive silicone rubber impregnation and adds dimensional stability and puncture resistance. This thin material keeps thermal resistance low and save space while providing electrical isolation.

Material Properties

- Assembly time reduced by 70% over grease & mica systems
- Puncture resistance; high thermal conductivity
- Electrically isolates power sources from heat sink devices
- Resists high pressure and deterioration
- Optional Adhesive available for ease of install
- UL94V-0 flammability rating, ROHS, halogen free
- Easy to assemble

Applications

- Automotive electronics
- Electronic modules for power devices Computers, servers, batteries
- Thermal modules
- Electrical insulation
- Communications

EVSC800FG

Color	Gray	Visual
Base	Fiber glass	* * *
Thickness (mm)	0.16~0.5mm	ASTM D751
Density (g/cm3)	2.2	ASTM D297
Hardness (Shore A)	45	ASTM D2240
Tensile Strength (psi)	450	ASTM D412
Applicable temp/℃	-50 to 200℃	* * *
Electrical		
Dielectric Breakdown Voltage	>4000V	ASTM D149
Dielectric constant (1MHz)	5.5	ASTM D150
Volume resistivity (Ω.cm)	5.0 X 1013	ASTM D257
Fire rating	V-0	UL 94
Thermal conductive		
Thermal conductivity(W/m.k)	0.8	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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- Electrically isolates power sources from heat sink devices
- Resists high pressure and deterioration
- Optional Adhesive available for ease of install
- UL94V-0 flammability rating, ROHS, halogen free
- Easy to assemble

Applications

- Automotive electronics
- Electronic modules for power devices Computers, servers, batteries
- Thermal modules
- Electrical insulation
- Communications

EVSC800-PI-2-K4

Item	SPEC	Test Method
Base	PI film	
Thickness(mm)	0.16±0.02	ASTM D374
Color	Gray	Visual
Applicable tempure (℃)	-50~200	***
Thermal conductivity(W/m.k)	0.9	ASTM D5470
Tensile Strength (KN/M)	5	ASTM D1458
Volume resistivity (Ω.cm)	1012	ASTM D257
Dielectric Breakdown Voltageh@AC	＞4000V	ASTM D149
Hardness (Shore A)	90±5	ASTM D2240
Tensile Strength (MPa)	35	ASTM D412
Elongation (%)	40	ASTM D412
Dielectric constant(1MHz)	5.0	ASTM D150
Fire rating	V-0	UL 94
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Material Properties

- Assembly time reduced by 70% over grease & mica systems
- Puncture resistance; high thermal conductivity
- Electrically isolates power sources from heat sink devices
- Resists high pressure and deterioration
- Optional Adhesive available for ease of install
- UL94V-0 flammability rating, ROHS, halogen free
- Easy to assemble

Applications

- Automotive electronics
- Electronic modules for power devices Computers, servers, batteries
- Thermal modules
- Electrical insulation
- Communications

EVSC800-PI-2-K10

Item	SPEC	Test Method
Base	PI film	
Thickness(mm)	0.16±0.02	ASTM D374
Color	Yellow	Visual
Applicable tempure (℃)	-50~200	***
Thermal conductivity(W/m.k)	1.3	ASTM D5470
Tensile Strength (KN/M)	5	ASTM D1458
Volume resistivity (Ω.cm)	1012	ASTM D257
Dielectric Breakdown Voltageh@AC	＞4000V	ASTM D149
Hardness (Shore A)	90±5	ASTM D2240
Tensile Strength (MPa)	35	ASTM D412
Elongation (%)	40	ASTM D412
Dielectric constant(1MHz)	3.7	ASTM D150
Fire rating	V-0	UL 94
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Material Properties

- Assembly time reduced by 70% over grease & mica systems
- Puncture resistance; high thermal conductivity
- Electrically isolates power sources from heat sink devices
- Resists high pressure and deterioration
- Optional Adhesive available for ease of install
- UL94V-0 flammability rating, ROHS, halogen free
- Easy to assemble

Applications

- Automotive electronics
- Adapter
- Communication equipment
- Motor Controller
- High pressure interface
- Semiconductor Optoelectronic Products

EVSC900FG

Color	Brick Red	Visual
Base	Fiberglass	* * *
Thickness (mm)	0.2~0.5mm	ASTM D751
Density (g/cm^3)	2.2	ASTM D297
Hardness (Shore A)	45	ASTM D2240
Tensile Strength (psi)	450	ASTM D412
Applicable tempure/ °C	-50 to 200 °C	* * *
Electrical		
Dielectric Breakdown Voltage@AC	>4000V	ASTM D149
Dielectric constant (1MHz)	5.5	ASTM D150
Volume resistivity (Ω.cm)	5.0 X 10^{13}	ASTM D257
Fire rating	V-0	UL 94
Thermal conductive		
Thermal conductivity(W/m.k)	2.0	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

Technical Data Sheet

Product Description

Thermal Insulating Sheet

Material Properties

- High thermal conductivity, low resistance
- Electrical insulation
- High pressure resistance
- High tensile strength

Also Available:

- Cut per drawing and custom shapes
- Optional adhesive

Applications

- Automotive electronics
- Adapter
- Communication equipment
- Motor Controller
- High pressure interface
- Semiconductor Optoelectronic Products

EVSC1000FG

Color		White		Visual	
Composition		Fiberglass		* * *	
Thickness (mm)		0.2~0.5mm		ASTM D751	
Hardness (Shore A)		90		ASTM D2240	
Pressure (Psi)	10	25	50	100	200
(℃*in2/W)	0.59	0.44	0.34	0.29	0.24
Applicable tempure℉/ ℃		-50 to 200℃		* * *	
Electrical					
Dielectric Breakdown Voltage@AC		>4000V		ASTM D149	
Dielectric constant (1MHz)		4.0		ASTM D150	
Volume resistivity (Ω.cm)		10^{11}		ASTM D257	
Fire rating		V0		UL 94	
Thermal conductive					
Thermal conductivity(W/m.k)		3.5		ASTM D5470	
RoHS		PASS		IEC 62321	
Halogen		PASS		EN14582	
REACH		PASS		EN14372	

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

Technical Data Sheet

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness, are naturally tacky and can be cut to any size or shape for easy installation

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF1000FG

Color	White	Visual
Thickness	0.15 ~ 15.0mm	ASTM D374
Specific Gravity	2.1g/cm3	ASTM D792
Thermal Conductivity	1.5 W/m.k	ASTM D5470
Base	Fiber glass	* * *
Hardness(Shore oo)	30-90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	40psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	6*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200°C	***
Thermal Resistance(1mm,@30psi)	0.9°C*in²/W	ASTM D5470
Compression Ratio(1mm,@30psi)	40%	***
Dielectric Constant@1 MHz	5.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

EVSF100FG-A1

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Color	White	Visual
Thickness	0.15 ~ 15.0mm	ASTM D374
Specific Gravity	2.1g/cm3	ASTM D792
Thermal Conductivity	1.5 W/m.k	ASTM D5470
Base	Fiber glass	* * *
Hardness(Shore oo)	30-90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	40psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	$6*10^{13}\Omega.cm$	ASTM D257
Operating Temperature	-50 ~ 200°C	***
Thermal Resistance(1mm,@30psi)	$0.9°C*in^2/W$	ASTM D5470
Compression Ratio(1mm,@30psi)	40%	***
Dielectric Constant@1 MHz	5.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

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Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF300

Color	Dark Gray	Visual
Thickness	0.15 - 15.0mm	ASTM D374
Specific Gravity	2.3g/cm3	ASTM D792
Thermal Conductivity	2.0 W/m.k	ASTM D5470
Hardness(Shore oo)	30~90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength	40psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200°C	***
Thermal Resistance(1mm,@30psi)	0.7°C*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	40%	***
Dielectric Constant@1 MHz	6.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF400

Color	Yellow	Visual
Thickness	0.15 ~ 10.0mm	ASTM D374
Specific Gravity	2.7g/cm3	ASTM D792
Thermal Conductivity	2.50 W/m.k	ASTM D5470
Hardness(Shore oo)	30~90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	40%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200°C	***
Thermal Resistance(1mm,@30psi)	0.5°C*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	30%	***
Dielectric Constant@1 MHz	7.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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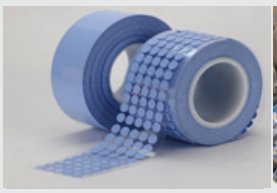

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF500

Color	Blue	Visual
Thickness	0.30~ 10.0mm	ASTM D374
Specific Gravity	2.9g/cm3	ASTM D792
Thermal Conductivity	3.0 W/m.k	ASTM D5470
Hardness(Shore oo)	30~90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	40%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200	***
Thermal Resistance(1mm,@30psi)	0.45 *in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	30%	***
Dielectric Constant@1 MHz	7.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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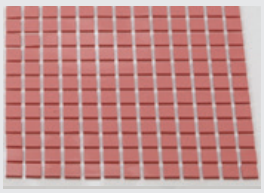

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF600

Color	Gray	Visual
Thickness	0.5-5.0mm	ASTM D374
Specific Gravity	3.20g/cm3	ASTM D792
Thermal Conductivity	5.0 W/m.k	ASTM D5470
Hardness(Shore oo)	40-90	ASTM D2240
Normal Hardness(Shore00)	40、60±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200℃	***
Thermal Resistance(1mm,@30psi)	0.31℃*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	25%	***
Dielectric Constant@1 MHz	9.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF600G

Color	Gray	Visual
Thickness	0.5-5.0mm	ASTM D374
Specific Gravity	3.30g/cm3	ASTM D792
Thermal Conductivity	6.0 W/m.k	ASTM D5470
Hardness(Shore oo)	40-90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>8000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200°C	***
Thermal Resistance(1mm,@30psi)	0.29°C*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	25%	***
Dielectric Constant@1 MHz	9.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVSF800

Color	Gray	Visual
Thickness	0.5 ~ 5.0mm	ASTM D374
Specific Gravity	3.40g/cm3	ASTM D792
Thermal Conductivity	8.0 W/m.k	ASTM D5470
Hardness(Shore oo)	40~80	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	15%	ASTM D412
Tensile Strength	20psi	ASTM D412
Dielectric Breakdown Voltageh@AC	>6000V/mm	ASTM D149
Flammability Rating	UL94 V-0	E355606
Volume resistivity	1*1013Ω.cm	ASTM D257
Operating Temperature	-50-150°C	***
Thermal Resistance(1mm,@30psi)	0.29°C*in2/W	ASTM D5470
Compression Ratio(1mm,@30psi)	30%	***
Dielectric Constant@1 MHz	10.0	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

Technical Data Sheet

EverTherm CS series is a composite material which offers extremely high thermal conductivity, low density and good durability. Carbon fiber is an anisotropic and offering a very high level of thermal conductivity in the Z axis. This silica gel sheet is very soft and well compressed, it is used to fill the interface of two substrates, ensuring air from the interface is discharged, and heat conduction dramatically improved. Thermal conductivity @ 25.0W/M.K

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good flexibility and high compression ratio

Adhesive optional:

-A1 equals single-sided adhesive
-A2 equals double-sided adhesive

Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

EVCSF25

Color	Black	visual
Thickness	0.5~ 20.0mm	ASTM D374
Metal	silicone	***
Filler	carbon fiber	***
Density	2.9g/cm3	ASTM D792
Thermal Conductivity	25.0W/m.k	ASTM D5470
Dielectric Breakdown Voltageh@AC	100V	ASTM D149
Hardness (Shore 00)	40~90	ASTM D2240
Normal Hardness(Shore00)	40/60±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Thermal Resistance(1mm,@40psi)	0.06 *in2/W	ASTM D5470
Operating Temperature(℃)	-50 ~ 160	ASTM D1329
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

Technical Data Sheet

EverTherm SH series is a highly sustainable and extremely versatile material. This product has uniform foam structure, excellent abrasion resilience, will not break down over time and is flame retardant. It can also be used for sound & heat insulation, moisture barrier, shock absorption, primarily for communications, electric vehicle (EV) power and electronics industries.

Material Properties

- Excellent flame retardancy
- Good electrical insulation
- Excellent elasticity high very low compression set
- Extreme temperature resistance, good sealing
- Will not break down over time

Applications

- Communications,
- Electric Vehicle energy
- Electronics,
- Lighting equipment cabinet
- Hardware and other fields

EVSH600

Parameter	Unit	Test Standard
Color	Visual	Gray
Thickness	mm	1.0-12
Density (25℃)	g/cm3	0.45
Hardness	shore C	5-85,Common 15/20
Substrate	Silicone	
Compression deformation (maximum)	%	70℃<1, 100℃<5
Compression stress	65kPa	ASTM D1056/compress 25% stress
Elongation	%	80
Flammability	UL94	V-0
Flame spread index	Ls	25
Vapor Density	Ds	Test in 4min < 50 Test in 1.5min < 20
Toxic gas diffusion level	SMP-800C	PASS
Water absorption (Room temperature 24hr)	%	1.4
Dielectric constant	1kHz	1.42
Dielectric strength	KV/mm	3.58
Dry arc resistance	s	92
Volume resistivity	Ω•cm	1015
Thermal conductivity	W/m.k	< 0.1
Low temperature deflection (-55℃)	ASTM D 1056	PASS
Recommend temperature	℃	-55 ~ 220
Recommended maximum temperature for intermittent use	℃	250
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

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EverTherm™

Technical Data Sheet

Phase Change Material (PCM)

EverTherm PCM Series is very soft and shapeable and exhibits excellent thermal conductivity in the vertical (z-plane) direction. This material is a solid material at room temperature. When exposed to 50-55°C it becomes a soft semi-flowing paste. This allows easy shaping conformation between 2 compressed surfaces. The material will return back into solid state when it reaches below 50-55°C temperature. It can also be customized into different shapes and sizes based on the requirements of the application.

Material Properties

- Excellent thermal conductivity in the vertical z-plane
- Strong interface wetting ability, long-term reliable thermal conductivity
- Good flexibility & compression ratio
- Effectively reduce the coating thickness of the material between the interface
- Flexible and can be easily converted to custom sizes
- Thin and lightweight

Applications

- Semiconductor device testing,
  - CPU, GPU, MCM
  Mobile phones & PC tablets, PCs, Servers, and cloud storage
- PDP, LED devices, IGBT Modules
- Optical communications equipment, medical equipment
- High frequency microprocessor
- Integrated Chip

EVSP205A

Item	Detection	Testing method
Color	Gray	Visual
Thickness(mm)	0.127	ASTM D751
Thickness tolerance	±0.015mm	ASTM D751
Density/cm3)	2.85	ASTM D297
Applicable temp	-40°C~ 125°C	***
Phase change temperature	50°C ~ 55°C	***
Volume Resistance (Ω.cm)	2.0 X 1010	ASTM D257
Thermal conductivity (W/m.K)	3.0	ASTM D5470
Dielectric constant(1MHZ)	3.0	ASTM D150
Thermal impedance@10psi(℃*in2/W)	0.05	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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EverTherm™

Technical Data Sheet

Phase Change Material (PCM)

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Material Properties

- Excellent thermal conductivity in the vertical z-plane
- Strong interface wetting ability, long-term reliable thermal conductivity
- Good flexibility & compression ratio
- Effectively reduce the coating thickness of the material between the interface
- Flexible and can be easily converted to custom sizes
- Thin and lightweight

Applications

- Semiconductor device testing, - CPU, GPU, MCM Mobile phones & PC tablets, PCs, Servers, and cloud storage
- PDP, LED devices, IGBT Modules
- Optical communications equipment, medical equipment
- High frequency microprocessor
- Integrated Chip

EVSP350P

Item	Detection	Testing method
Color	Green	Visual
Reinforcement Carrier	**	***
Thickness (mm)	0.20~0.50	ASTM D374
Elongation (%) Elongation	40	ASTM D882A4
Tensile strengthTensile Strength (Psi)	7100	ASTM D882A4
Continuous Operating temperaturep(℃)	257	***
Phase Change Temp(℃)	55	ASTM D3418
Dielectric Breakdown Voltage(Vac)	8KV	ASTM D149
Dielectric constant(1MHz)	4.5	ASTM D150
Volume resistivity(Ω)	1012	ASTM D257
Thermal conductivity(W/m.k)	1.8	ASTM D5470
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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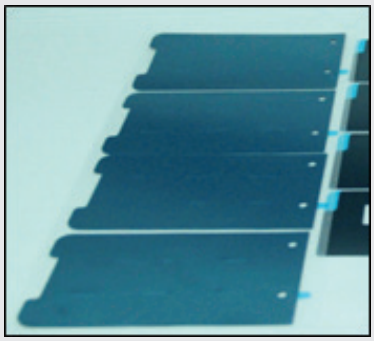
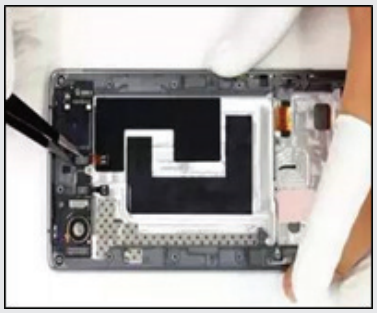
EverTherm™

Technical Data Sheet

EverTherm SR600-A-B has a unique layered structure and crystal orientation. It is comprised of artificial graphite which has a super high level of Thermal Conductivity in the planar direction. This material is made of graphite, which can be converted/cut into various shapes.





EVSR600-A-B

Item	Detection	Testing method
Protective film Color	Black	Visual
Total Thickness (mm)	0.06±0.003	ASTM D374
Graphite Substrate Thickness (mm)	0.025	ASTM D374
Composition	Black PET film, artificial graphite	***
Insulating adhesive tape	Yes	***
Density(g/cm3)	1.7~2.0	ASTM D792
Thermal conductivity@XY(W/m.k)	1500	ASTM E1461
Thermal conductivity@Z(W/m.k)	>30	ASTM E1461
Heat(J/g.k)	0.85	***
Applicable tempure (℃)	-40 to 130	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

Applications

- Applications
- Mobile phones
- Computers, tablets
- TV
- Thermal module
- Router

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EverTherm™

Technical Data Sheet

Product Description

Graphite Copper Foil

Thermally Conductive Graphite Copper is a thermal interface material with super high conductivity generated from a carbon/copper film structure. Nano-copper/carbon foil thermally conductive tape uses copper foil as a carrier and is coated with a thermally conductive acrylic adhesive. It provides an excellent heat conduction path between the heating element and the heat sink.

Material Properties

- High thermal conductivity
- Excellent Shielding properties Lightweight/ thin
- Good shielding effectiveness
- Excellent heat-transfer path between the heat-generator and heat sink

Applications

- Automotive electronics
- Computers and servers
- Communication equipment
- Consumer electronics
- Aerospace and medical devices
- LED lighting equipment
- Displays

EVSU010-1/2

Item	Test	Test method
Copper foil thickness（mm）	0.05±0.005	ASTM D374
Coating thickness（mm）	0.003±0.001	ASTM D374
Total thickness（mm）	0.10±0.005	ASTM D374
Proportion（g/cm3）	7.70±0.50	ASTM D792
Temperature range（℃）	'-40-200	***
Thermal Conductivity（W/m-K）	400	ASTM D5470
Resistance（Ω.cm）	≤0.02	ASTM D257
Adhesion（kgf/inch）	>0.6	GB/T 2792-1998
Printability	Nano carbon coating	***
Width（mm）	380mm;500mm; 600mm	Base of copper substrate
Length（M）	50M/ volume	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

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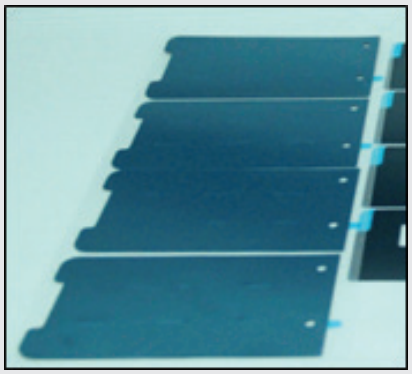
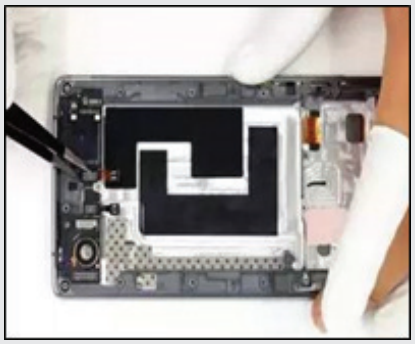
EverTherm™

Technical Data Sheet

EverTherm SR600-A-P is a composite of artificial graphite film and foam. The result of this construction causes plane heat conduction and vertical heat insulation which have excellent buffering capabilities.





Applications

- Applications
- Mobile phones
- Computers, tablets
- TV
- Thermal module
- Router

EVSR600-A-P

Item	Detection	Testing method
Foam Color	Black	Visual
Total Thickness (mm)	0.17±0.003	ASTM D374
Graphite Substrate Thickness (mm)	0.025	ASTM D374
Composition	Artificial graphite, PET tape, foam	***
Density(g/cm3)	1.7~2.0	ASTM D792
Thermal conductivity@XY(W/m.k)	1500	ASTM E1461
Thermal conductivity@Z(W/m.k)	>30	ASTM E1461
Heat(J/g.k)	0.85	***
Applicable tempure (℃)	-40 to 130	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Material Properties

- High thermal conductivity
- Excellent Shielding properties Lightweight/ thin
- Good shielding effectiveness
- Excellent heat-transfer path between the heat-generator and heat sink

Applications

- Automotive electronics
- Computers and servers
- Communication equipment
- Consumer electronics
- Aerospace and medical devices
- LED lighting equipment
- Displays

EVSU010-1/2

Item	Test	Test method
Copper foil thickness（mm）	0.05±0.005	ASTM D374
Coating thickness（mm）	0.003±0.001	ASTM D374
Total thickness（mm）	0.10±0.005	ASTM D374
Proportion（g/cm3）	7.70±0.50	ASTM D792
Temperature range（℃）	'-40-200	***
Thermal Conductivity（W/m-K）	400	ASTM D5470
Resistance（Ω.cm）	≤0.02	ASTM D257
Adhesion（kgf/inch）	>0.6	GB/T 2792-1998
Printability	Nano carbon coating	***
Width（mm）	380mm;500mm; 600mm	Base of copper substrate
Length（M）	50M/ volume	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

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EverTherm™

Technical Data Sheet

EverTherm SY series is a new type of aerogel thermal insulation film which is a thin-film nano thermal insulation material. Aerogel is the world's lightest solid material offering the best thermal insulation performance. Its pore diameter is ~ 20nm, which is smaller than the free path of air (70nm). The air molecules in the pores lose their ability to flow freely, thus achieving ultra-high thermal insulation performance. In addition, by using the heat insulation film and the heat dissipation film in combination, the uniformity of the heat insulation can be improved. For related information, please consult the CR Technology technical team.

Material Properties

- Thin film: 80μm ~ 350 μm
- The combined use of heat dissipation film can provide a variety of thermal solutions.

Applications

- Wearable terminal
- Smart phone
- LCD TV
- Tablet PC
- Digital cameras and various electronic devices that require heat insulation

EVSY300

Item	Detection	Testing method
Thickness	80μm ;130μm 350μm	ASTM D751
Substrate (Base)	non	***
Thermal conductivity (W/(m•K))	0.018 ~ 0.022	ASTM D5470
Operating temperature range (℃)	-20 ~ 120	***
Long-term heat resistance temperature (℃)	120	ASTM D2240
Flame Rating	Not flame retardant	***
Size	300*200	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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